

IN THE CLAIMS

1-28 (Canceled)

29. (Previously Presented) A circuit device, comprising:
a dielectric substrate
at least one conductive pattern formed in the dielectric substrate;
a first earthed conductor formed on a first surface of the dielectric substrate,
wherein the first earthed conductor does not cover the entire area of the first surface; and
a second earthed conductor formed on a second surface of the dielectric substrate,
the second surface opposed to the first surface, wherein the first earthed conductor is connected
with the second earthed conductor only along the periphery of the dielectric substrate.

30. (New) A circuit device as claimed in claim 29, comprising a pattern formed on
said earthed conductor, and that enables to change the area and position of the earthed conductor.

31. (New) A circuit device as claimed in claim 30, comprising said pattern, which
formed one side, or plural sides of outside layer of said dielectric substrate.

32. (New) A circuit device as claimed in claim 31, comprising a same or different
pattern, which is formed one side, or plural sides of outside layer of said dielectric substrate.

33. (New) A circuit device as claimed in claim 30, comprising a said pattern having a
lattice shaped said earthed conductor.